What is claimed is:

10

- 1. A surface-mount crystal oscillator, comprising:
- a crystal unit; and
- a receptacle for accommodating an IC chip, said receptacle being bonded to a rear surface of said crystal unit;

wherein said receptacle comprises a bottom wall and sidewalls, a concavity is formed in at least one principal surface of said receptacle, the sidewalls surrounding said concavity are opened on at least one longitudinal end of said receptacle, and a notch portion is formed in said bottom wall at a position corresponding to the opened portion of said sidewalls.

- 2. The surface-mount crystal oscillator according to claim 1, wherein said IC chip, together with said crystal unit, constitutes an oscillation circuit.
- 3. The surface-mount crystal oscillator according to claim 1, wherein an electronic component is arranged on said bottom wall at the position corresponding to the opened portion of said sidewalls.
- 4. The surface-mount crystal oscillator according to claim 3, wherein said electronic component is a chip

capacitor.

- 5. The surface-mount crystal oscillator according to claim 1, wherein said receptacle is a mounting substrate having a substantially rectangular planar shape, and said sidewalls surrounding said concavity are opened at both longitudinal ends of said mounting substrate.
- 6. The surface-mount crystal oscillator according to claim 5, wherein chip capacitors are arranged on said bottom wall at positions corresponding to each opened portion of said sidewalls.
- 7. The surface-mount crystal oscillator according to claim 1, wherein said crystal unit and said receptacle are each constructed as separate units, and are assembled by bonding said crystal unit and said receptacle together.
- 8. The surface-mount crystal oscillator according to claim 5, wherein said crystal unit and said mounting substrate are each constructed as separate units, and are assembled by bonding said crystal unit and said mounting substrate together.
 - 9. The surface-mount crystal oscillator according to claim 5, wherein said mounting substrate is composed of

ceramic.